



# **SSCE5V082P1**

Ultra-low Capacitance Bidirectional Micro Packaged TVS Diodes for ESD Protection

## • Description

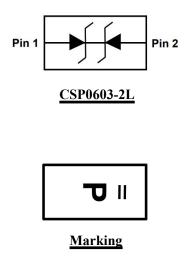
The SSCE5V082P1 is designed with SSC Punch-Through process TVS technology to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed, USB 3.0 super speed, VGA, DVI, HDMI,SDI and other high speed line applications.

It has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by ESD(electrostatic discharge), and EFT (electrical fast transients).

#### • Feature

- $\Rightarrow$  50W peak pulse power (tP = 8/20us)
- ♦ CSP0603-2L Package
- ♦ Working voltage: 5V
- ♦ Low clamping voltage
- ♦ Low capacitance(<0.25pF) for high-speed interfaces</p>
- ♦ No insertion loss to 10.0GHz
- ♦ RoHS compliant
- ♦ Complies with following standards: -IEC61000-4-2(ESD) ±20Kv(contact),±20kV(air)
  -IEC61000-4-4 (EFT) 40A (5/50ns)
  -IEC61000-4-5 (Lightning) 9A (8/20us)

PIN configuration



#### • Applications

- ♦ High Speed Line : USB1.0/2.0/3.0/3.1, VGA, DVI, SDI
- High Definition Multi-Media Interface (HDMI1.3/1.4/2.0)
- ♦ Serial and Parallel Ports
- ♦ Notebooks, Desktops, Servers
- ♦ Projection TV
- ♦ Cellular handsets and accessories
- ♦ Portable instrumentation
- ♦ Peripherals

#### • Mechanical data

- ♦ Lead finish:100% matte Sn(Tin)
- $\diamond$  Mounting position: Any
- ♦ Qualified max reflow temperature:260°C
- ♦ Device meets MSL 1 requirements
- ♦ Pure tin plating:  $7 \sim 17$  um
- ♦ Pin flatness:≤3mil

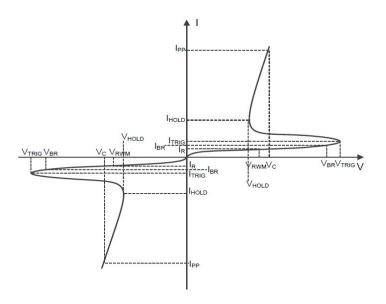
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# SSCE5V082P1

## • Electronic Parameter

Symbol	Parameter
V <sub>RWM</sub>	Peak Reverse Working Voltage
I <sub>R</sub>	Reverse Leakage Current @ V <sub>RWM</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
IT	Test Current
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
P <sub>PP</sub>	Peak Pulse Power
V <sub>TRIG</sub>	Reverse Trigger Voltage
V <sub>TRIG</sub>	Reverse Trigger Current
V <sub>HOLD</sub>	Reverse Holding Voltage
I <sub>HOLD</sub>	Reverse Holding Current
CJ	Junction Capacitance



# • Absolute maximum rating @TA=25°C

Parameter	Symbol	Value	Unit		
Peak Pulse Power (8/20us)	P <sub>PP</sub>	50	W		
Peak Pulse Current (8/20us)	I <sub>PP</sub>	9	А		
ESD Rating per IEC61000-4-2: Contact	V	20	<b>V</b> V		
Air	V <sub>ESD</sub>	20	KV		
Storage Temperature	T <sub>STG</sub>	-55/+150	°C		
Operating Temperature	TJ	-55/+150	°C		
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C		

# • Electrical Characteristics @TA=25°C

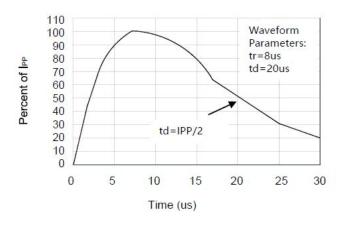
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working Voltage	V <sub>RWM</sub>			5	5.5	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>T</sub> = 1mA	6	9.5		V
Reverse Leakage Current	I <sub>R</sub>	$V_{RWM} = 5.5V$			1	μΑ
	V <sub>C</sub>	$I_{PP} = 1A, t_P = 8/20us$		3.2		V
Clamping Voltage		$I_{PP}=9A, t_P=8/20us$		5.5	8	V
Clamping Voltage	V <sub>C2</sub>	$I_{PP}=16A, t_P=100ns$		6.5		V
Dynamic resistance	R <sub>DYN</sub>			0.23		Ω
	CJ	$V_{R}$ =1.0V, f = 1MHz		0.14	0.18	pF
Junction Capacitance		$V_{R}$ =1.0V, f = 1GHz		0.13		pF



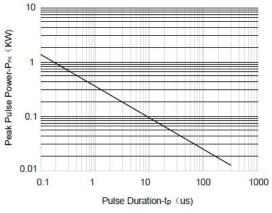
% of Rated Power or Ipp

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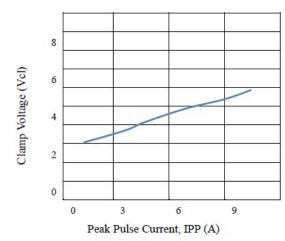
## • Typical Performance Characteristics





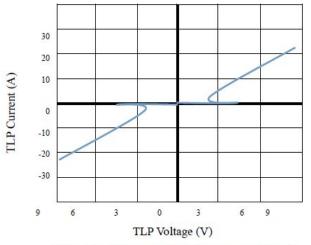


Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

Ambient Temperature-TA (2)



Clamping Voltage Vs Peak PulseCurrent(ITLP)

Clamping Voltage Vs Peak PulseCurrent( Ipp)



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## • Package Information

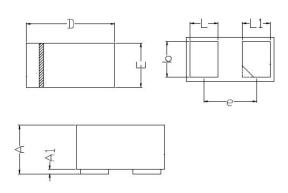
## **Ordering Information**

Device	Package	Qty per Reel	Reel Size	
SSCE5V082P1	CSP0603-2L	9000	7 Inch	

### **Mechanical Data**

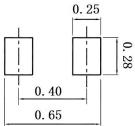
Case:CSP0603-2L

Case Material: Molded Plastic. UL Flammability



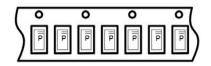
DIM	Millimeters				
	Min	Max			
Α	0.230	0.330			
A1	0.000 0.050				
A3	0.102REF				
D	0.550	0.650			
E	0.250	0.350			
b	0.220 0.270				
L	0.120 0.170				
L1	0.120	0.170			
е	0.40BSC				

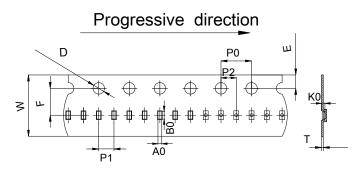
#### **Recommended Pad outline**



### CSP0603 Reel Dim

## **Device Orientation in Tape**





PACKAGE	w	E	F	PO	D	P2	P1	т	A0	В0	к0
CSP0603	8mm	1.75mm	3.5mm	4mm	1.5mm	2mm	2mm	0.23mm	0.34mm	0.67mm	0.4mm
CSP0003	±0.1	±0.1	±0.05	±0.1	±0.1	±0.05	±0.1	±0.02	±0.05	±0.05	±0.05



## • History Version

V1.0	First edition	2021-09-06
V1.1	1.Revise Marking	2022-05-09
	2.Correction of electrical characteristic curve	

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